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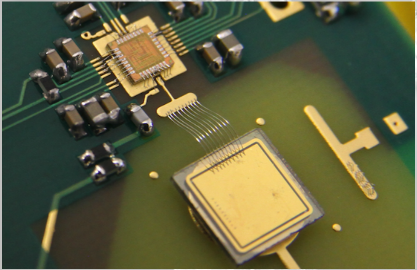

High Rate Tests of CVD Diamond Pad Detectors

RD42 Meeting

Michael Reichmann

26th April 2019

Table of Contents

Section 1

Motivation

Diamond as Detector Material

- innermost tracking layers $\rightarrow$ highest radiation damage $\mathcal{O}\left(\mathrm{GHz/cm^2}\right)$
- current detectors is designed to survive $\sim$12 month in High-Luminosity LHC
- $\rightarrow$ **CERN R&D for more radiation tolerant detector designs and/or materials**

Diamond as Detector Material

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Diamond as Detector Material:

- properties
  - radiation tolerant
  - isolating material
  - high charge carrier mobility
  - **smaller signal than in silicon with same thickness (large bandgap)**
  - **after $1 \cdot 10^{16}\,\mathrm{n/cm^2}$ the mean drift path in diamond larger than in silicon**

Diamond as Detector Material

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Work of RD42:

- investigate signals and radiation tolerance in various detector designs:
  - Pad Detectors $\rightarrow$ whole diamond as single cell readout
  - Pixel Detectors $\rightarrow$ diamond sensor on pixel readout chip
  - 3D Pixel Detectors $\rightarrow$ 3D diamond detector on pixel readout chip

Diamond as Detector Material

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Work of RD42:

- investigate signals and radiation tolerance in various detector designs:
  - **Pad Detectors** → this talk
  - Pixel Detectors
  - 3D Pixel Detectors

Section 2

Website

Website

- finished analysis of all the pad data taken at PSI (Oct 2015 - Oct 2018)
- most of the following results on the website (https://diamond.ethz.ch/psi)

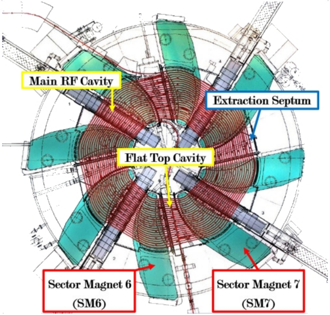
Section 3

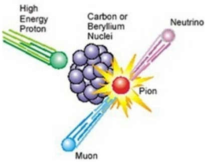
Setup


SCHWEISSWERK BÜLACH AG

Test Site

- High Intensity Proton Accelerator (HIPA) at PSI (Cyclotron) $\rightarrow$ beam line PiM1
- clean positive pion beam ($\sim$98 % π^+) with momentum of 260 MeV/c
  - ¾ smaller signals than at CERN! (120 GeV/c)
- **tunable particle fluxes from $\mathcal{O}\left(1\,\mathrm{kHz/cm^2}\right)$ to $\mathcal{O}\left(10\,\mathrm{MHz/cm^2}\right)$**
- **significant multiple scattering $\rightarrow$ worsens resolution**





Final Setup

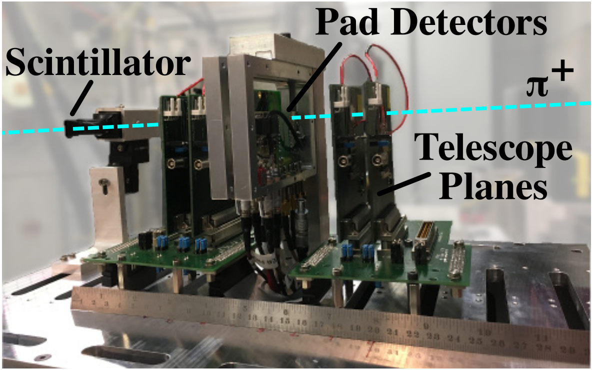


Figure: Modular Beam Telescope

- 4 tracking planes → trigger (fast-OR) with adjustable effective area
- diamond pad detectors in between tracking planes
- fast scintillator

Setup Development

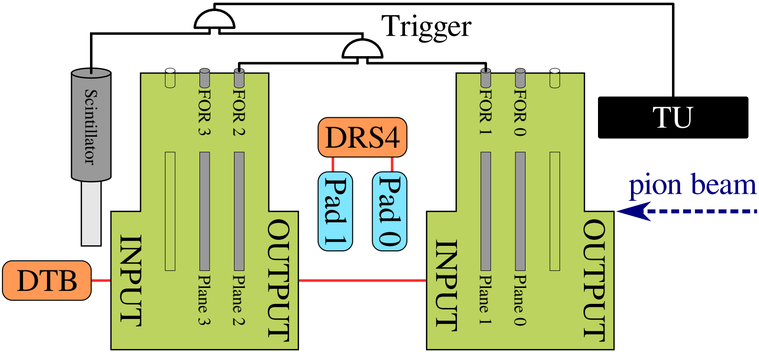


Figure: Current Setup (Aug16 - Oct18)

- scintillator → precise trigger timing of $\mathcal{O}\,(1\,\mathrm{ns})$
- Trigger Unit (TU) → strongly simplifying setup
- global trigger → (Plane 1 AND Plane 2) AND Scintillator

Section 4

Measurements

Tested Detectors

Name	Nick	Producer	Type	T [μm]	Irr_{max}	Comments
S129	S129	e6	scCVD	528	0	reference
IIa-3	IIa-3	IIa	scCVD	?	$5 \cdot 10^{13}$	
SiD1	SiD1	PSI	Si-Diode	300	0	calibration
SiD2	SiD2	IJS	Si-Diode	100	0	calibration
2A87-e	2A87-e	II-VI	pCVD	?	$5 \cdot 10^{13}$	
II6-78	poly-A	II-VI	pCVD	?	0	
II6-79	poly-B	II-VI	pCVD	?	0	fixed surface
II6-81	poly-D	II-VI	pCVD	?	$1 \cdot 10^{14}$	
II6-94	94	II-VI	pCVD	?	0	also as pixel
II6-95	95	II-VI	pCVD	?	$5 \cdot 10^{14}$	also as pixel
II6-96	96	II-VI	pCVD	?	0	
II6-97	97	II-VI	pCVD	?	$3.5 \cdot 10^{15}$	irradiation studies
II6-B2	B2	II-VI	pCVD	455	$8 \cdot 10^{15}$	irradiation studies
II6-E5	E5	II-VI	pCVD	?	0	bcm prime test
II6-H0	H0	II-VI	pCVD	?	0	bcm prime test
II6-H8	H8	II-VI	pCVD	?	0	bcm prime test

Table: Pad Detector Information.

2015 - 2016

Diamond	May15	Aug15	Oct15	Aug16	Oct16
S129	✓(0)	✓(0)	✓(0)	✓(0)	✓(0)
IIa-3	✗	✗	✓($5 \cdot 10^{13}$)	✗	✗
SiD1	✗	✗	✗	✓(0)	✓(0)
SiD2	✗	✗	✗	✗	✓(0)
2A87-e	✗	✗	✓($5 \cdot 10^{13}$)	✗	✗
II6-78	✓(0)	✗	✗	✗	✗
II6-79	✓(0)	✓(0)	✗	✗	✗
II6-81	✓($1 \cdot 10^{14}$)	✗	✓($1 \cdot 10^{14}$)	✗	✗
II6-94	✓(0)	✗	✗	✓(0)	✗
II6-95	✓(0)	✗	✗	✓($5 \cdot 10^{14}$)	✗
II6-96	✓(0)	✗	✗	✗	✗
II6-97	✗	✓(0)	✓(0)	✓($5 \cdot 10^{14}$)	✓($1.5 \cdot 10^{15}$)
II6-B2	✗	✓(0)	✓($5 \cdot 10^{14}$)	✓($1 \cdot 10^{15}$)	✓($2 \cdot 10^{15}$)
II6-E5	✗	✗	✗	✗	✗
II6-H0	✗	✗	✗	✗	✗
II6-H8	✗	✗	✗	✗	✗

Table: Pad Detector Timeline. Irradiation in n/cm^2 in parenthesis.

2017 - 2018

Diamond	May17	Jul17	Aug17	Aug18	Oct18
S129	✓(0)	✓(0)	✓(0)	✓(0)	✗
IIa-3	✗	✗	✗	✗	✗
SiD1	✗	✗	✗	✗	✗
SiD2	✓(0)	✓(0)	✓(0)	✓(0)	✗
2A87-e	✗	✗	✗	✗	✗
II6-78	✗	✗	✗	✗	✗
II6-79	✗	✓(0)	✗	✗	✗
II6-81	✗	✗	✗	✗	✗
II6-94	✗	✗	✗	✗	✗
II6-95	✗	✗	✗	✗	✗
II6-96	✗	✗	✗	✗	✗
II6-97	✗	✓($1.5 \cdot 10^{15}$)	✓($3.5 \cdot 10^{15}$)	✗	✗
II6-B2	✗	✓($2 \cdot 10^{15}$)	✓($4 \cdot 10^{15}$)	✓($8 \cdot 10^{15}$)	✗
II6-E5	✗	✓*(0)	✗	✗	✗
II6-H0	✓*(0)	✓*(0)	✗	✗	✗
II6-H8	✗	✗	✗	✓(0)	✓*(0)

Table: Pad Detector Timeline. Irradiation in n/cm^2 in parenthesis. * - BCMPrime devices.

Scan Types

Diamond	Rate Scan	Voltage Scan	Random Scan
S129	✓	✓	✗
IIa-3	✓	✗	✗
SiD1	✓	✓	✗
SiD2	✓	✓	✗
2A87-e	✓	✗	✗
II6-78	✓	✗	✗
II6-79	✓	✗	✗
II6-81	✓	✓	✗
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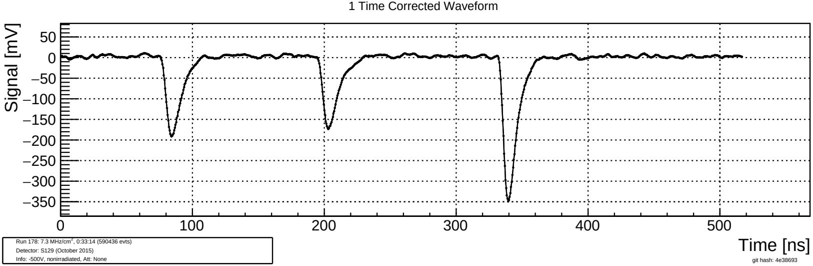
II6-97	✓	✗	✓
II6-B2	✓	✓	✓
II6-E5	✓	✗	✗
II6-H0	✓	✗	✗
II6-H8	✓	✗	✗

Table: Pad Detector Scan Types.

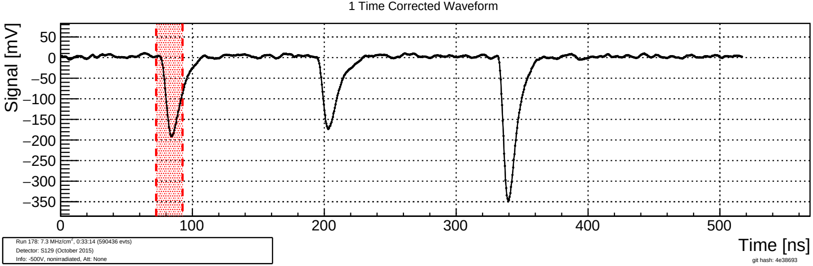
Section 5

Integration

Region and Range

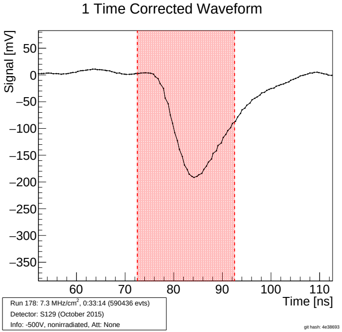


Region and Range



- define signal region: one bunch wide (20 ns) around the triggered signal

Region and Range



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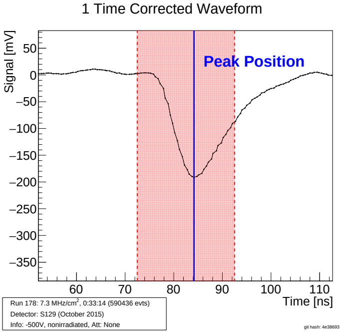
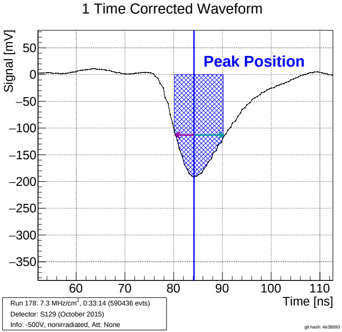


- define signal region: one bunch wide (20 ns) around the triggered signal
- find the peak within the signal region by max value

Region and Range



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- signal: integrate asymmetrically around the peak (optimisation by SNR)

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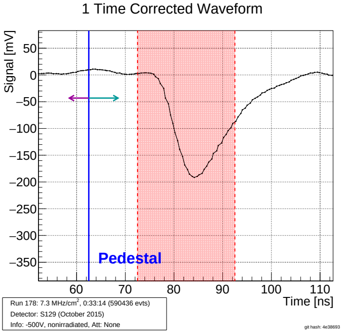

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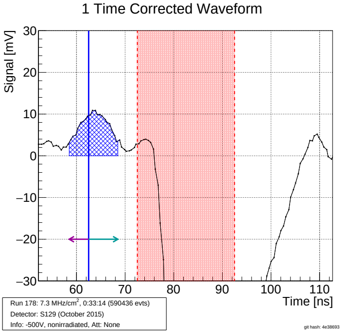

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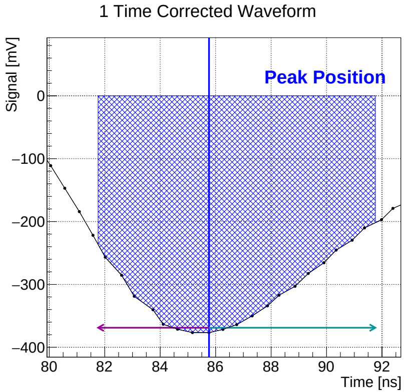
Integration



- integration performed on time corrected waveform
- single bin integral: (w) times the mean of the two values: $w \cdot (v1 + v2)/2$
- sum up the single integrals + interpolated edges to get the exact integration width
- normalise by the width of the integral

Section 6

Conclusion

Conclusion

- empty
- moreempty
- moremoreempty

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